

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4037647

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ELEMENT SIX TECHNOLOGIES LIMITED	09/02/2016
RECEIVING PARTY DATA	
Name:	RFHIC CORPORATION
Street Address:	RFHIC BLDG. 41-14, BURIM-RO 170 BEON-GIL,
Internal Address:	DONGAN-GU, ANYANG-SI, GYEONGGI-DO
City:	ANYANG-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	14055
PROPERTY NUMBERS Total: 2	
Property Type	Number
Patent Number:	9418833
Patent Number:	9214407
CORRESPONDENCE DATA	
Fax Number:	(408)716-4985
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Address Line 1:	P.O. BOX 62312
Address Line 4:	SUNNYVALE, CALIFORNIA 94088-2312
NAME OF SUBMITTER:	CHUNG SIK PARK
SIGNATURE:	/Chung.Park/
DATE SIGNED:	09/03/2016
Total Attachments: 4	
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CONFIRMATORY ASSIGNMENT

PARTIES:

- (1) **ELEMENT SIX TECHNOLOGIES LIMITED**, a company registered in England & Wales under company number 08206603 having its registered office at Global Innovation Centre, Fermi Avenue, Harwell Oxford, Didcot, Oxfordshire, OX11 0QR, UK; (the "ASSIGNOR") and
- (2) **RFHC CORPORATION**, a Republic of Korea company headquartered in Anyang-Si, Republic of Korea, with offices in Morrisville, North Carolina, United States of America, (the "ASSIGNEE");

each a "PARTY" and together the "PARTIES".

1. DEFINITIONS:

For the purposes of this Assignment:

- 1.1 "PATENTS" shall mean, collectively and severally, the patents and patent applications listed in the SCHEDULE to this Assignment.
- 1.2 "INVENTIONS" shall mean the inventions to which the PATENTS relate.

2. WHEREAS:

- 2.1 By virtue of an agreement between the PARTIES dated 15th July 2016 (the "AGREEMENT"), the ASSIGNOR has assigned to the ASSIGNEE all its right title and interest in and to the INVENTIONS and the PATENTS.
- 2.2 For the avoidance of doubt, and so as to confirm ASSIGNEE's legal title to the same, the Parties have agreed to execute this Assignment for the purpose of ensuring that all ASSIGNOR's rights in the INVENTIONS and PATENTS and all other intellectual property rights relating thereto are vested in ASSIGNEE.

3. IT IS AGREED THAT:

In consideration of the sum of \$1 (one United States Dollar) paid by ASSIGNOR to ASSIGNEE, the receipt of which is hereby acknowledged:

- 3.1 ASSIGNOR as necessary hereby confirms the assignment of and assigns to ASSIGNEE, and ASSIGNEE as necessary hereby confirms its acceptance of and accepts all ASSIGNOR's property right title and interest in and to the INVENTIONS and PATENTS for all relevant states including without limitation:
 - (a) the right to apply for and obtain patents in respect of the INVENTIONS in any country in the world;
 - (b) all right, title and interest in and to the PATENTS and all patent applications, patents and supplementary protection certificates which may now or at any time in the future derive or result or claim priority from the same or otherwise relate to the INVENTIONS, including without limitation any divisionals, continuations, continuations-in-part, reissues, re-examination certificates, post-grant reviews, inter partes reviews, supplemental examinations, extensions, renewals and registrations in relation to any thereof and all and any other rights in the inventions comprised in any of the same (hereinafter collectively and severally "the PATENT RIGHTS");
 - (c) the benefit of all priority dates;
 - (d) the right to seek and obtain registrations in any country in the world in respect of any patent deriving from the PATENTS or otherwise included in the PATENT RIGHTS;
 - (e) the right to sue for and obtain injunctive relief, damages and all other relief in respect of any infringement or misuse (whether past present or future) of any of the PATENT RIGHTS or of the rights conferred by publication of any of the same.

- 3.2 Each PARTY authorises and requests his/her professional representative before any national or regional patent office to insert an appendix signed and dated by the professional representative detailing the filing date and application number of any patent application, patent and/or supplementary protection certificates which may now or at any time in the future derive or result or claim priority from the PATENTS where needed for effective recordal of any such patent application or patent at any national or regional patent office.
- 3.3 ASSIGNOR hereby covenants and agrees to and with ASSIGNEE that, at the time of execution and delivery of the AGREEMENT, ASSIGNOR was the sole and lawful owner of the entire right, title, and interest in and to the INVENTIONS and PATENTS, and that ASSIGNOR had good and full right and lawful authority to sell and convey the same.
- 3.4 ASSIGNOR will, without further consideration, communicate to the ASSIGNEE any facts known to the ASSIGNOR regarding the INVENTION and the PATENTS, sign all lawful papers, execute all oaths, assignments, powers of attorney, applications and any other paper desired by ASSIGNEE to obtain, perfect, or secure to ASSIGNEE any and all of the rights, titles and interests herein conveyed, and to maintain, enforce, and defend these rights, titles and interests in any country in the world. ASSIGNOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE under this clause 3.4.
- 3.5 At the request and expense of the ASIGNEE, ASSIGNOR will testify in any legal proceeding to obtain, perfect, or secure to ASSIGNEE any and all of the rights, titles and interests herein conveyed, and to maintain, enforce, and defend these rights, titles and interests in any country in the world. ASSIGNOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE under this clause 3.5.
- 3.6 ASSIGNOR hereby agrees to execute all such documents and do all such things as may be required by the law of any country in order to record the PATENTS and any other PATENT RIGHTS in the name of ASSIGNEE.
- 3.7 This Assignment shall be governed by the laws of New York, United States of America, and the parties submit to the exclusive jurisdiction of the courts of North Carolina, United States of America in respect of any dispute relating to this Assignment.

Signed on behalf of
ELEMENT SIX TECHNOLOGIES LIMITED

Signature: *David Tintch*
 Name: DANIEL TINTCH
 Title: Head of R&D Bio Dev
 Date: 2nd September 2016

Signed on behalf of
RFHIC CORPORATION

Signature: *[Signature]*
 Name: Deoksoo Cho
 Title: CEO
 Date: 31/8/2016

SCHEDULE

US Family Reference	Country	Application Number, Application Date (Filed-on Date)	Publication Number (Publication Date)	Grant Number (Grant Date)	Parent Application (unless where directly from priority/provisional applications)	Priority/Provisional Application Number (Priority/Provisional Application Date)	Inventor(s)	Title	US Case Reference
PF1130	GB	1222341.8 12-Dec-2012 (12-Dec-2012)	GB2497665 (19-Jun-2013)	GB2497665 (23-Jul-2014)		GB Priority Application 1121666.0 (16-Dec-2011)	MOLLART, Timothy Peter	Synthetic Diamond Coated Compound Semiconductor Substrates	PF1130-GB-2
	US	147362647 12-Dec-2012 (04-Jun-2014)	US20140339684 (20-Nov-2014)		National phase of International Application PCT/EP2012/075252 filed 12-Dec-2012, published as WO2013087766 on 20-Jun-2013	US Provisional Application 61576883 (16-Dec-2011)			PF1130-US-0
PF1200	US	13439750 19-Nov-2013 (30-Apr-2015)	US20150391922 (15-Oct-2015)	US9214407 (15-Dec-2015)	National phase of International Application PCT/EP2013/074158 filed 19-Nov-2013, published as WO2014078836 on 30-May-2014	US Provisional Application 61728929 (21-May-2012)	TWITCHEN, Daniel James	Synthetic Diamond Heat Spreaders	PF1200-US-0
	GB	131171.5 04-Dec-2013 (04-Dec-2013)	GB2510468 (06-Aug-2014)	GB2510468 (08-Jun-2016)		GB Priority Application 1361560.7 (29-Jan-2013)			PF1200-GB-0
PF1254	EP	1381597.8 04-Dec-2013 (28-May-2015)	EP2936530 (28-Oct-2015)JP		National Phase of International Application PCT/EP2013/075557 filed on 04-Dec-2013, published as WO2014095373 on 26-Jun-2014	GB Priority Application 1222798.9 (18-Dec-2012)	MOLLART, Timothy Peter; HANG, Qianzhong; EDWARDS, Michael John; ALLSOPP, Duncan William Edward;	Substrates for Semiconductor Devices	PF1254-EP-0
	JP	2015-348336 04-Dec-2013 (17-Jun-2015)	JP2016071450 (10-Mar-2016)			GB Priority Application 1310939.1 (05-Jan-2013)	BOWEN, Christopher Elyse; WANG, Wang Wang		PF1254-JP-2
PF1321	US	14698256 04-Dec-2013 (28-May-2015)	US20160186762 (30-Jun-2016)			US Provisional Application 61738641 (18-Dec-2012)			PF1321-US-0
	GB	1521646.8 09-Dec-2015 (09-Dec-2015)	GB2534674 (03-Aug-2016)			US Provisional Application 6209377 (18-Dec-2014)	MASSER-FALL, Francoz; FRANCIS, Daniel; LOWE, Frank Yannis;	Compound Semiconductor Device Structures Comprising Polycrystalline CVD Diamond	PF1321-GB-2
PF1322	WO	PCT/EP2015/079084 09-Dec-2015 (09-Dec-2015)	WO2016096551 (23-Jun-2016)			GB Priority Application 1502954.9 (23-Feb-2015)	TWITCHEN, Daniel James		PF1321-WO-0
	GB	1521647.6 09-Dec-2015 (09-Dec-2015)	GB2534675 (03-Aug-2016)			US Provisional Application 6209377 (18-Dec-2014)	LOWE, Frank Yannis; MASSER-FALL, Francoz; FRANCIS, Daniel;	Compound Semiconductor Device Structures Comprising Polycrystalline CVD Diamond	PF1322-GB-2
PF1322	WO	PCT/EP2015/079061 09-Dec-2015 (09-Dec-2015)	WO2016096556 (23-Jun-2016)			GB Priority Application 1502898.2 (18-Feb-2015)	TWITCHEN, Daniel James		PF1322-WO-0
	US								

E6 Family Reference	Country	Application Number, Application Date (Filed-on Date)	Publication Number (Publication Date)	Grant Number (Grant Date)	Parent Application (unless where directly from priority-provisional applications)	Priority/Provisional Application Number (Priority/Provisional Application Date)	Inventors)	Title	E6 Case Reference
PF1333	GB	1608246.9 11-May-2016 (11-May-2016)	Not yet published			US Provisional Application 62/161636 (14-May-2015)	FRANCIS, Daniel	Method of Fabricating Diamond Semiconductor Substrates	PF1333-GB-2
	WO	WO/2016/060493 11-May-2016 (11-May-2016)	Not yet published			GB Priority Application 1309766.0 (05-Jan-2015)			PF1333-WO-0
PF1330	US	62/237786 20-Nov-2015 (Provisional Application) 1521836.5					FRANCIS, Daniel, LOWE, Frank Yantis, PEARSON, Michael Ian	Mounting of Semiconductor-Chip Diamond Wafers for Device Processing	PF1330-GB-0
	GB	11-Dec-2015 (Priority Application)							PF1330-GB-0